

VERTICAL BALL GRID ARRAY INTEGRATED CIRCUIT PACKAGE

ABSTRACT OF THE DISCLOSURE

An integrated circuit package (30, 32) for vertical attachment as part of a high density module (200) comprising a carrier (70) having an opening (86), routing strips (82), conduits (84) and side surface terminals (100), the side surface terminals (100) disposed on a side surface (92), which side surface is common to the carrier (70) and the integrated circuit package 30, 32. An adhesive layer (60), which attaches a silicon chip (50) to a carrier (70), wire bonding (80) electrically connecting the silicon chip (50) to the routing strips (82) and potting material (90) filling the opening (86), are also disclosed.

Figure 1